

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A surface acoustic wave device, comprising:

a surface acoustic wave element;

an electronic component that drive controls the surface acoustic wave element;

a first substrate that defines an opening and which has a first connecting terminal electrically connected to the electronic component, the electronic component being disposed in the opening of the first substrate;

a second connecting terminal formed in the vicinity of the opening, and electrically connected to the first connecting terminal;

a second substrate which is mounted so that one face side is joined to the opening of the first substrate and an other face side allows the surface acoustic wave element to be electrically connected to the second connecting terminal; and

a cap which is joined to the first substrate and has a second hollow component that hermetically seals the surface acoustic wave element.
2. (Original) The surface acoustic wave device according to Claim 1, the first substrate and the second substrate being joined on a lateral face side of the second substrate with a sealant.
3. (Previously Presented) The surface acoustic wave device according to claim 1, the second substrate and the cap being joined to the first substrate, respectively with a same sealant.
4. (Previously Presented) The surface acoustic wave device according to claim 2, the sealant being made of at least one of a conductive brazing metal and a conductive adhesive.

5. (Previously Presented) The surface acoustic wave device according to claim 2, the sealant being made of a glassy material.

6. (Original) The surface acoustic wave device according to Claim 1, further including a grounding electrode formed on the one face side of the second substrate.

7. (Original) The surface acoustic wave device according to Claim 1, the second substrate including a ceramic single plate.

8. (Original) The surface acoustic wave device according to Claim 1, the electronic component being a flip-chip mounted to the first substrate.

9. (Original) The surface acoustic wave device according to Claim 1, the surface acoustic wave element being mounted on the second substrate with an adhesive, and the electronic component being mounted on the first substrate with a same adhesive as that used to mount the surface acoustic wave element.

10.-16. (Canceled)

17. (Previously Presented) The surface wave acoustic device according to claim 1, further including a hollow holding component disposed within the opening of the first substrate, the hollow holding component defining an axial hole, the electronic component being disposed within the axial hole.